



WANSEMI
万芯半导体

WP8810E

Enhancement Mode N-Channel Power MOSFET

TSSOP8/NMOS/20V/ ± 12 V/0.7V/5A/13.5m Ω

Rev0.8

20V, 13.5mΩ, 5A, N-Channel Enhancement Mode Power MOSFET

1.Features

- ◆ High Power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface Mount Package
- ◆ ESD Rating: HBM 2KV

V _{DS} Typ	R _{DS(on)} Typ.	I _D Max.
20V	13.5mΩ @ 4.5V	5A
	18mΩ @ 2.5V	

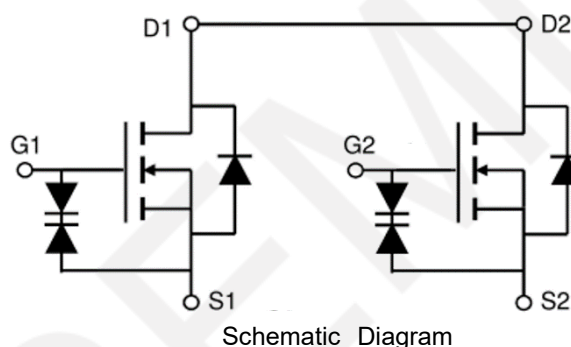
2.Applications

- ◆ Battery protection
- ◆ Load Switch
- ◆ Power management



TSSOP8

Pin Description



3.Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.
WP8810E	8810E	TSSOP8	5,000	80,000

4.Absolute Max Ratings at Ta=25°C (Note1)

Parameter	Symbol	Maximum	Units
Drain to Source Voltage	V _{DSS}	20	V
Gate to Source Voltage	V _{GSS}	±12	V
Drain Current-Continuous	I _D	5	A
Pulsed Drain Current	I _{DM}	20	A
Power Dissipation	P _D	0.9	W

Note 1 : Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

5.Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction to Ambient (Note 2)	R _{θJA}	139	°C/W

Note 2 : When mounted on 1 inch square copper board t ≤ 10sec The value in any given application depends on the user's specific board design.

6. Electrical Characteristics at Ta=25°C (Note 3)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 250\mu A, V_{GS} = 0V$	20	23	-	V
Zero-Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{DS} = 250\mu A$	0.4	0.7	1.0	V
Drain to Source On-State Resistance	$R_{DS(on)}$	$I_D = 5A, V_{GS} = 4.5V$	-	13.5	17	m Ω
		$I_D = 3A, V_{GS} = 2.5V$	-	18	23	m Ω
Diode Forward Voltage	V_{SD}	$I_S = 5A, V_{GS} = 0$	-	0.84	1.2	V
Input Capacitance	C_{iss}	$V_{GS} = 0V,$ $V_{DS} = 10V,$ Frequency=1.0MHz	-	545	-	pF
Output Capacitance	C_{oss}		-	103	-	pF
Reverse Transfer Capacitance	C_{rss}		-	90	-	pF
Turn-ON Delay Time	$t_{d(on)}$	$V_{DS} = 10V,$ $V_{GS} = 5V,$ $R_{GEN} = 3\Omega,$ $R_L = 1.5\Omega$	-	0.5	-	ns
Turn-ON Rise Time	t_r		-	1	-	ns
Turn-OFF Delay Time	$t_{d(off)}$		-	12	-	ns
Turn-ON Fall Time	t_f		-	4	-	ns
Total Gate Charge	Q_g	$V_{DS} = 10V,$ $V_{GS} = 4.5V,$ $I_D = 5A$	-	8	-	nC
Gate- Source Charge	Q_{gs}		-	2.5	-	nC
Gate-Drain Charge	Q_{gd}		-	3	-	nC

Note 3: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

7. Typical electrical and thermal characteristics

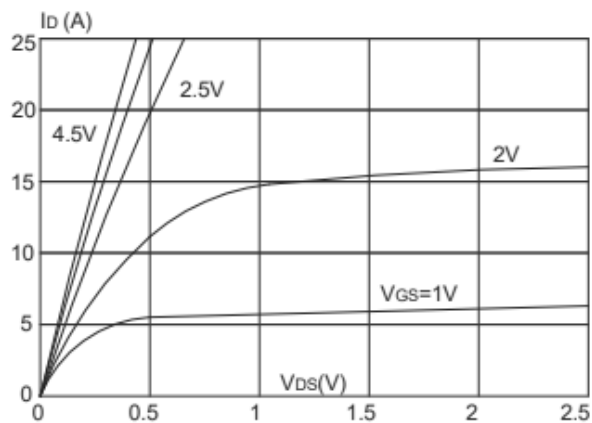


Figure 1 On-Region Characteristics

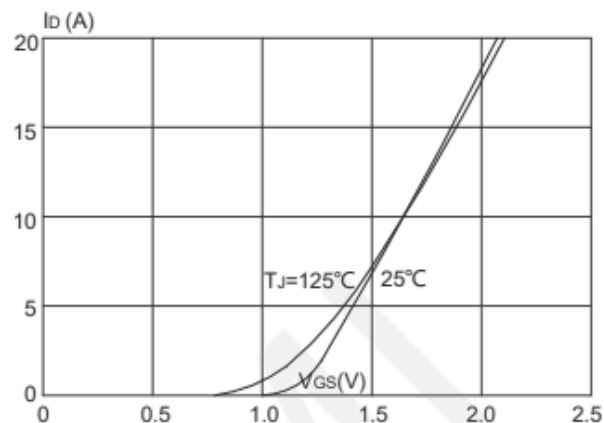


Figure 2 Transfer Characteristics

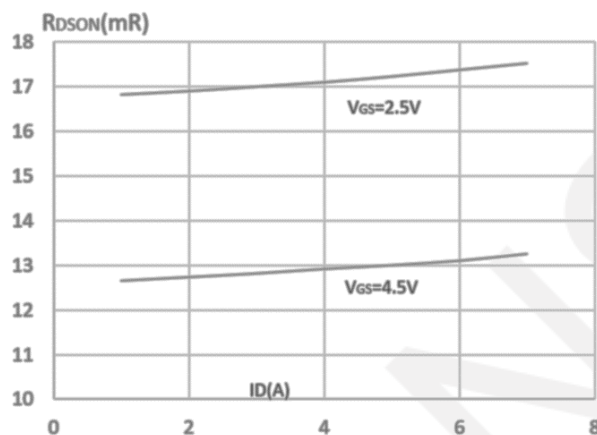


Figure 3 On-Resistance vs. Drain Current and Gate Voltage

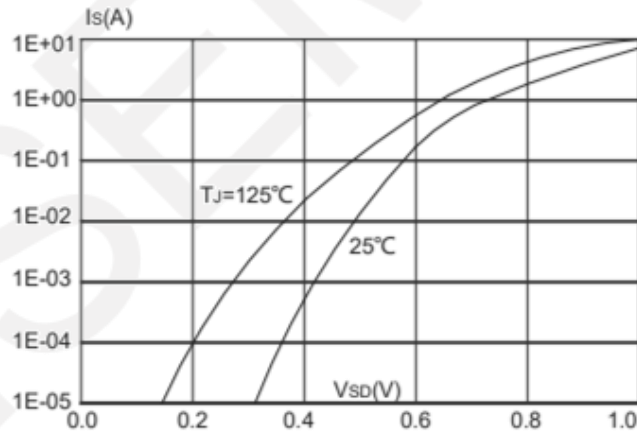


Figure 4 Body Diode Characteristics

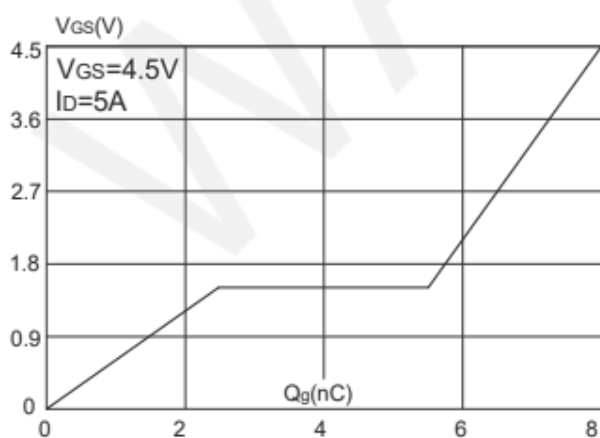


Figure 5 Gate Charge Characteristics

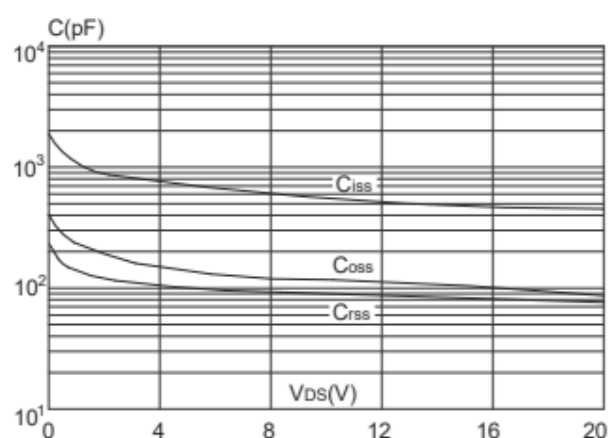


Figure 6 Capacitance Characteristics

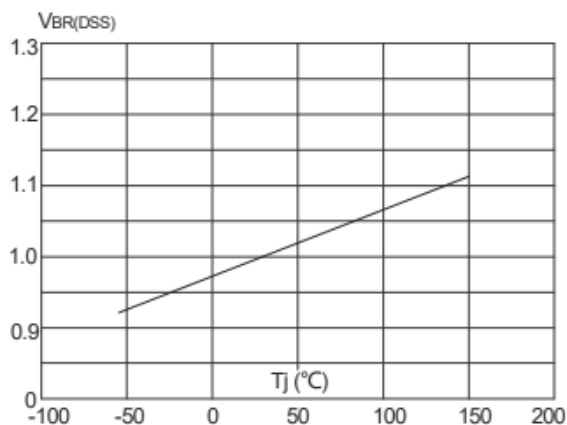


Figure 7 Normalized Breakdown Voltage vs. Junction Temperature

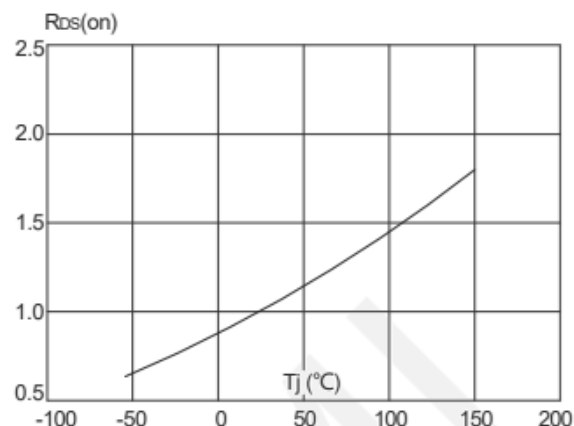


Figure 8 Normalized on Resistance vs. Junction Temperature

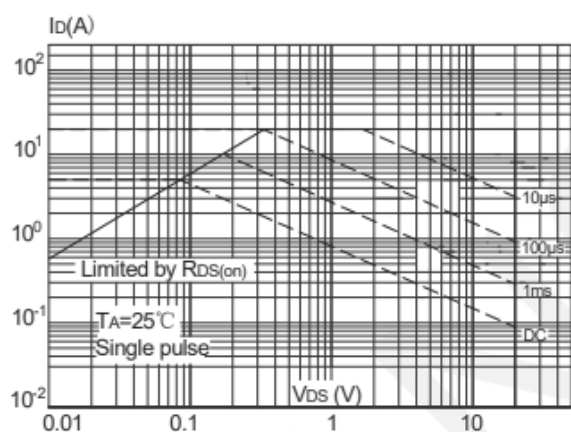


Figure 9 Maximum Forward Biased Safe Operating Area

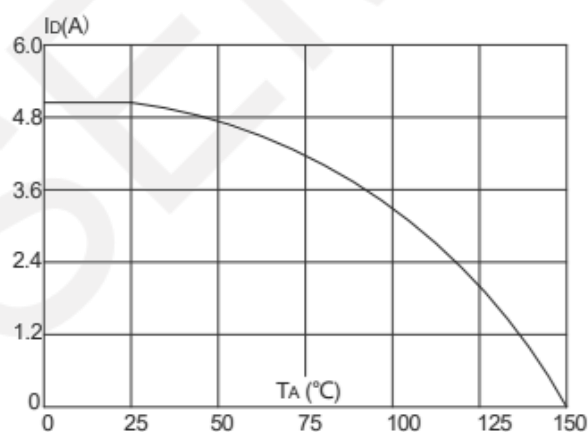


Figure 10 Single Pulse Power Rating Junction-To-Ambient

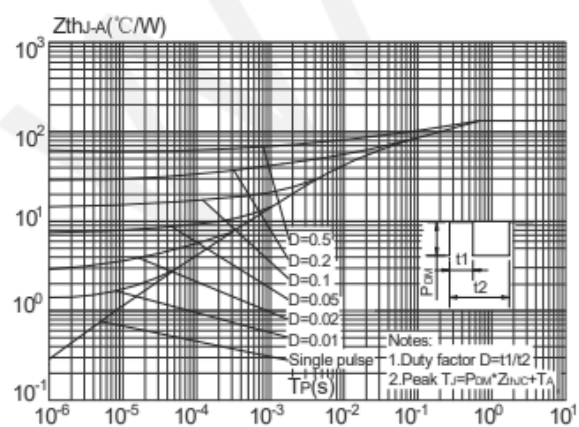
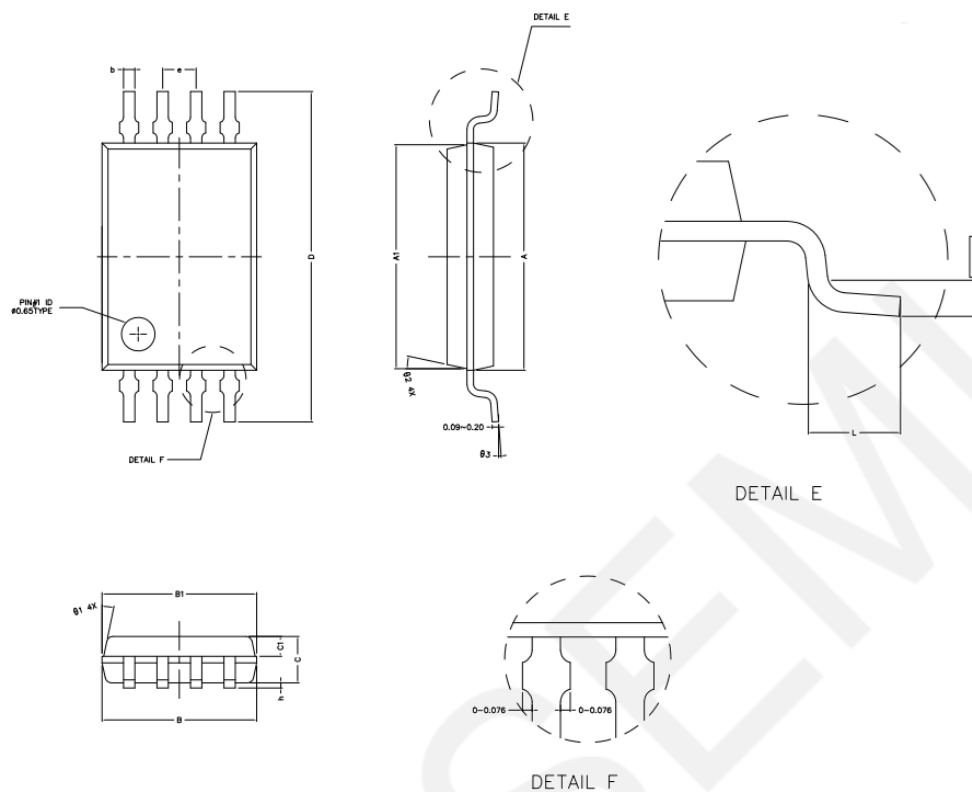


Figure11 Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

8.Package Dimensions



COMMON DIMENSIONS (UNITS OF MEASURE IS mm)			
	MIN	NORMAL	MAX
A	4.300	4.400	4.500
A1	4.240	4.340	4.440
B	3.050	3.150	3.250
B1	2.840	2.940	3.040
C	0.850	0.900	0.950
C1	0.337	0.387	0.437
D	6.250	6.400	6.550
L	0.450	0.600	0.750
b	0.170	0.220	0.300
h	0.050	0.100	0.150
e	0.650TYPE		
θ_1	12° TYPE		
θ_2	12° TYPE		
θ_3	0° ~ 7°		

9.Important Notice

WAN SEMICONDUCTOR (NINGBO) CO.,LTD reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services and to discontinue any product or service. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to WANSEMI’s terms and conditions of sale supplied at the time of order acknowledgment.

WANSEMI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in WANSEMI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent WANSEMI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

WANSEMI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using WANSEMI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

No WANSEMI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Unless WANSEMI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use, WANSEMI will not be responsible for any failure of such components to meet such requirements.